

# **Advances in Technology for High Power CATV Gain Blocks and the Related Challenges in Linearity Testing During Design and Volume Production**





## The Engine for HFC: CATV Gain Blocks



# Agenda

- **Gain Blocks for CATV networks**
- **Evolution of semiconductor technology**
- **Packaging and thermal design**
- **Linearity characterization and test development**
- **High volume assembly and test**

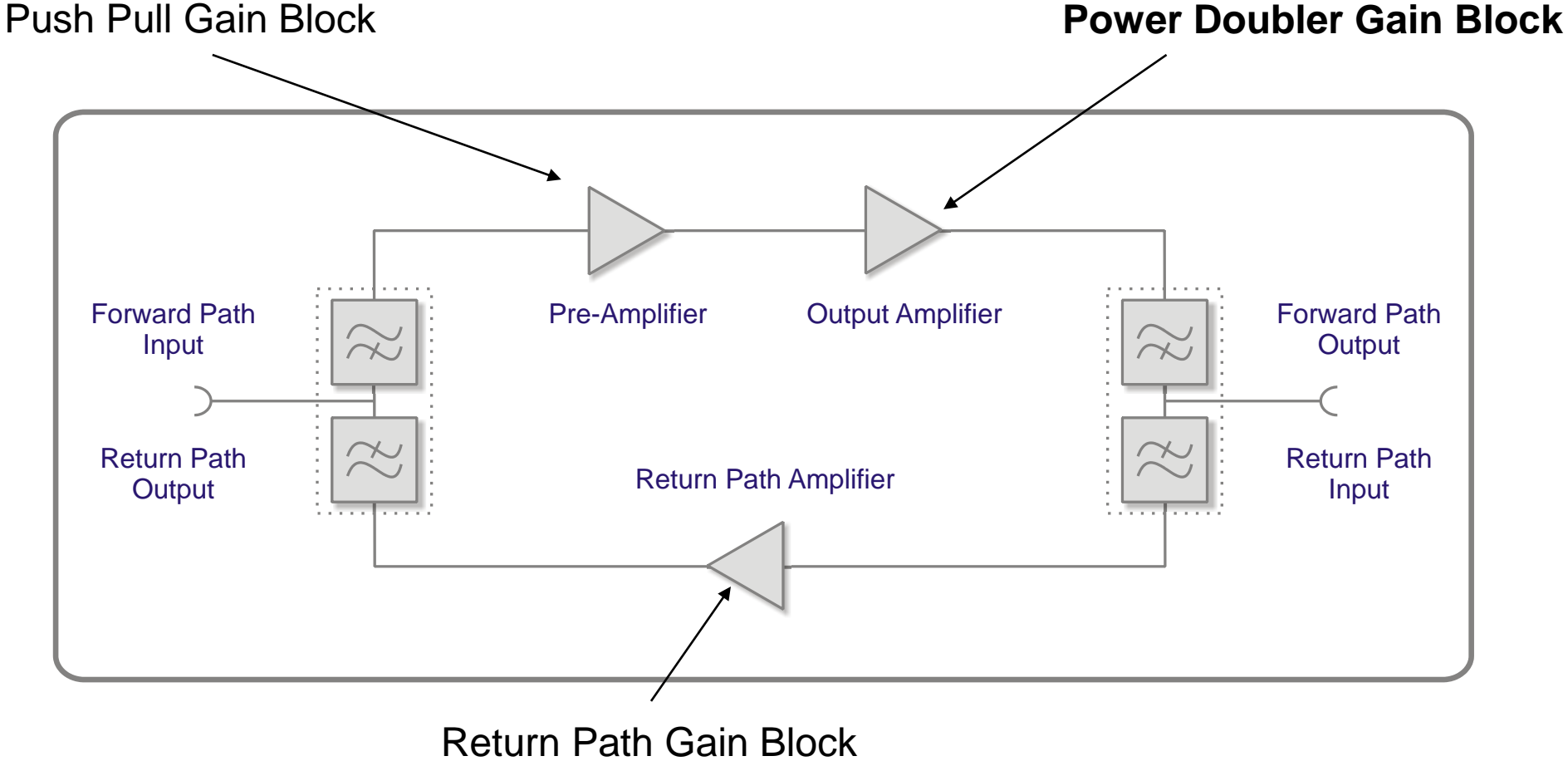


# GAIN BLOCK FOR CATV NETWORKS



# CATV Amplifier

## Simplified Block Diagram



# CATV Power Doubler Gain Blocks

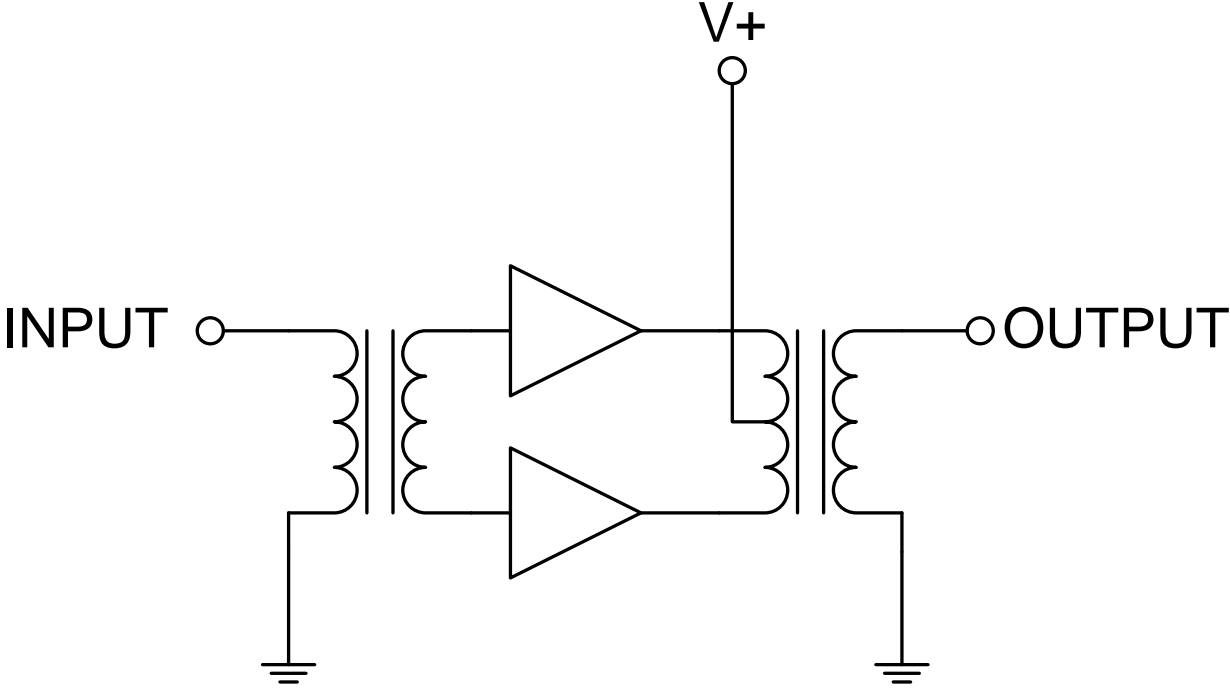
## Key Features

- **Extremely robust**
- **Extremely reliable**
- **Extremely wide bandwidth (more than 5 octaves)**
- **Extremely linear**
- **Extremely high linear output power**



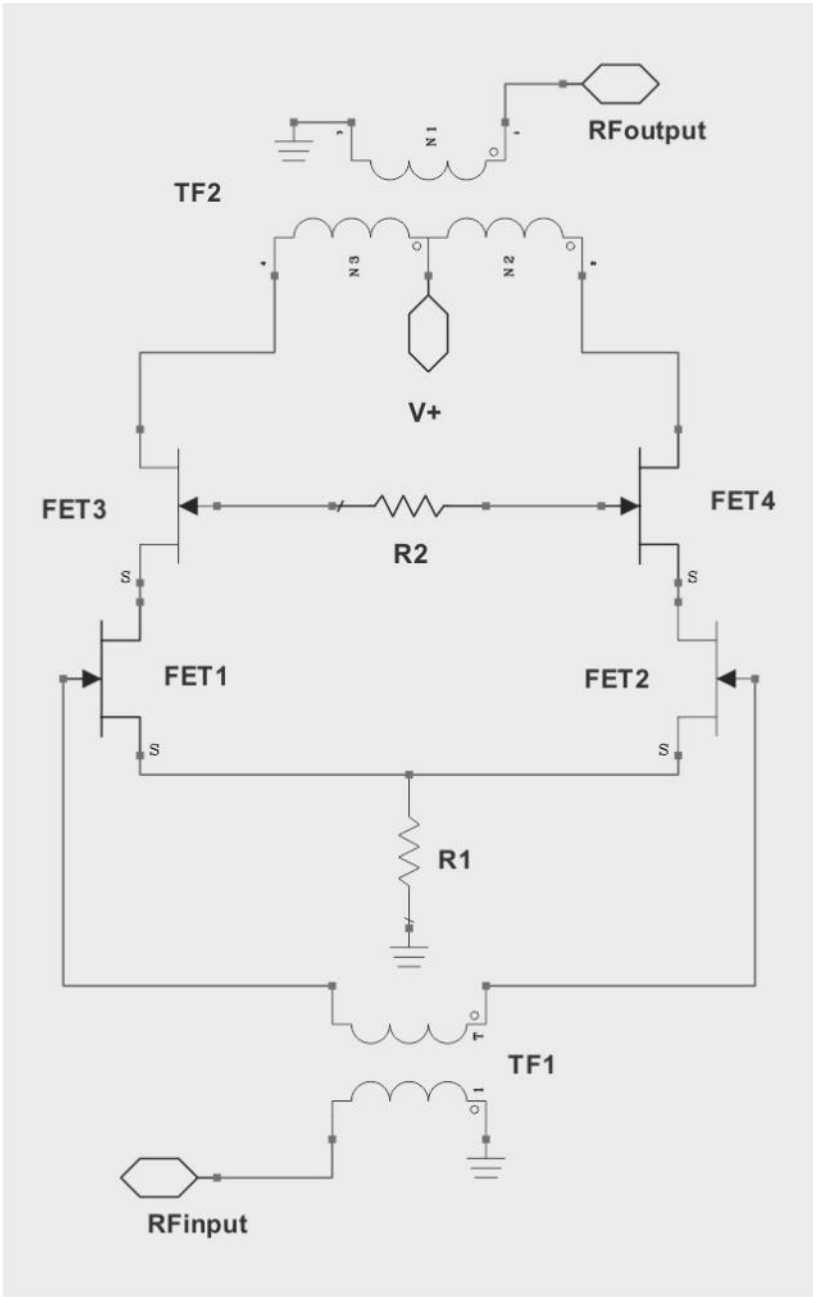
# CATV Gain Block

## Block Diagram



# CATV Gain Block

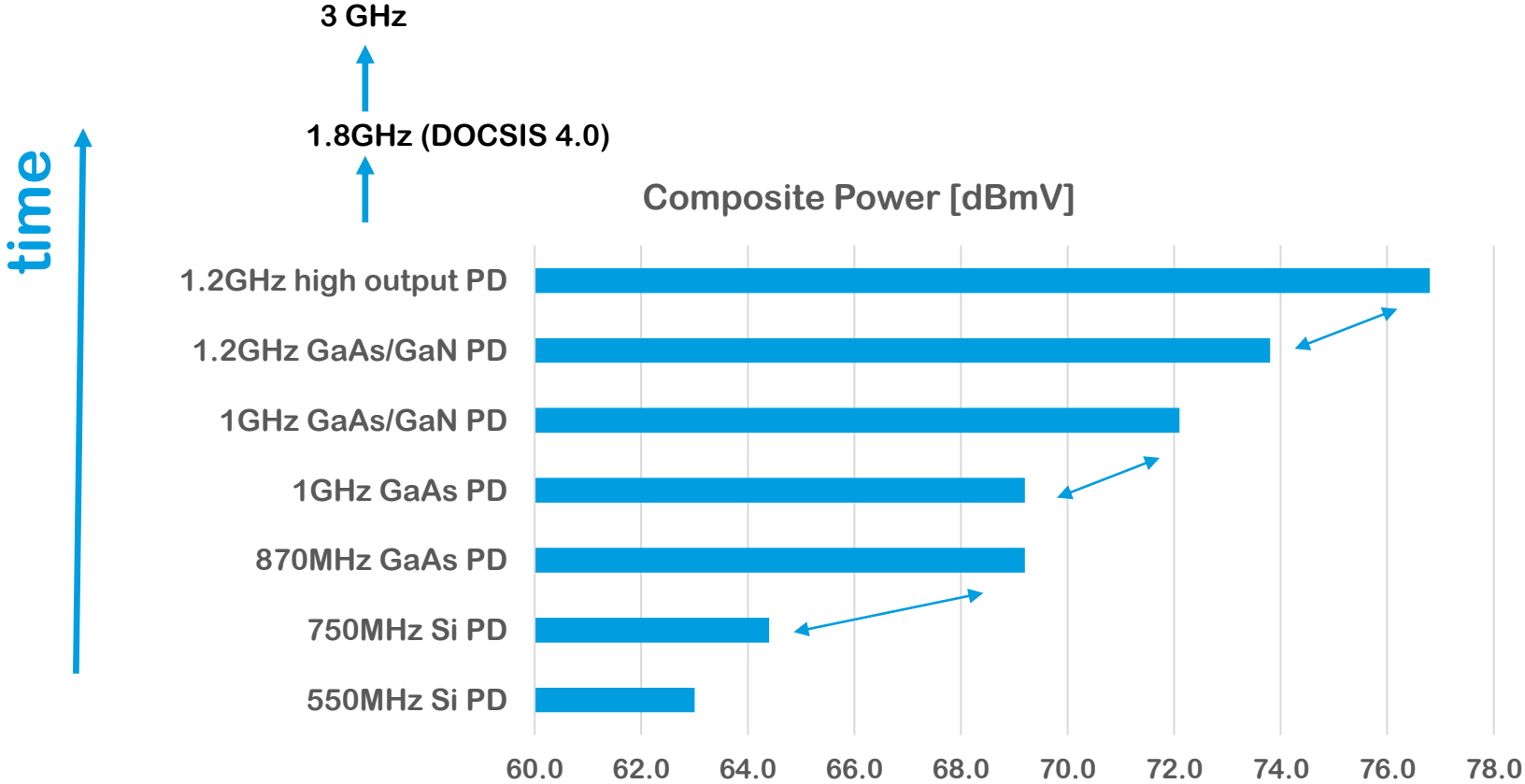
## Simplified Schematic





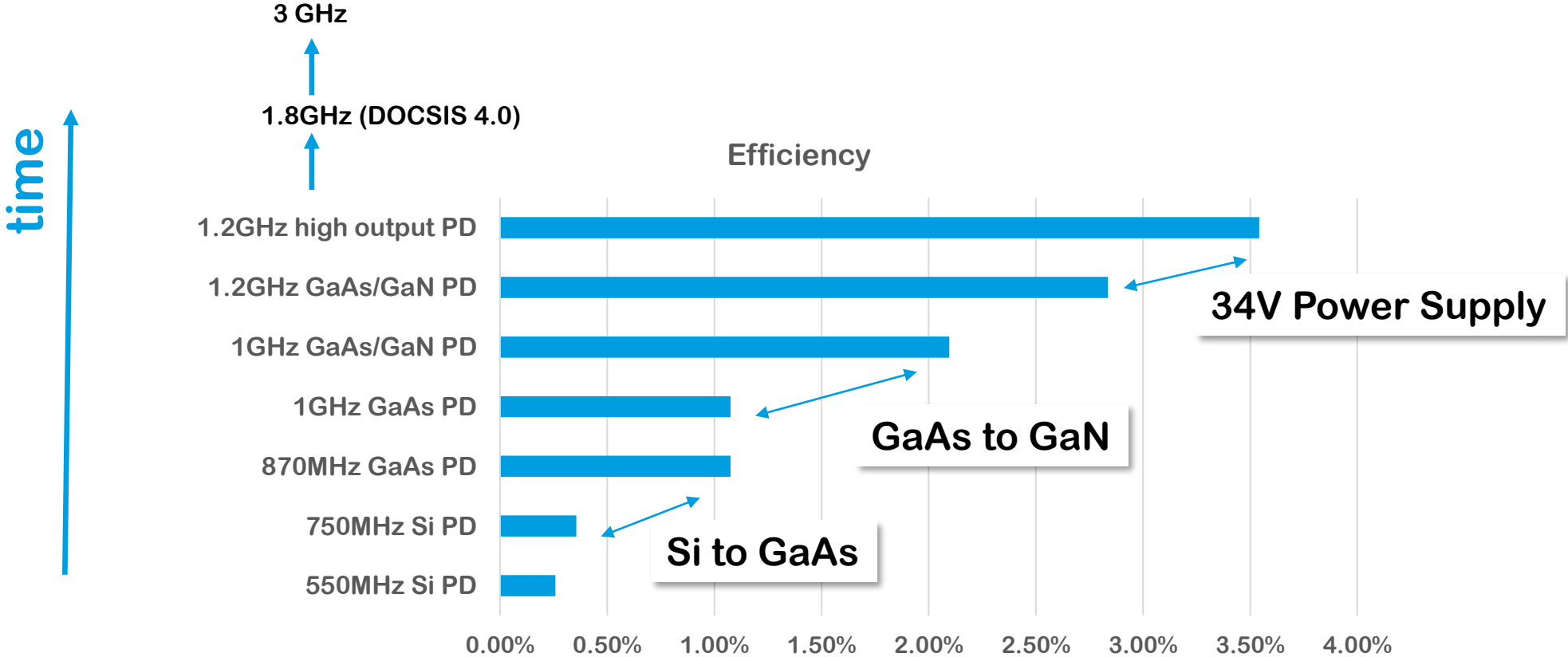
# Advances in Linear Output Power

## Efficiency and Composite Output Power



# Advances in Linear Output Power

## Efficiency and Composite Output Power



# SEMICONDUCTOR EVOLUTION



# Semiconductor Evolution for CATV

## GaAs versus Si

- Higher energy bandgap of GaAs (1.43 eV for GaAs vs. 1.11eV for Si)
  - Better isolator
- Higher electron mobility of GaAs compared to Si
  - Enables higher frequencies and bandwidths
- Thermal Design
  - FET design of GaAs transistors enable assembly directly on heat-sink
  - Si bipolar transistor require isolating layer
- FET design offers lower third order distortion because of its square law property

$$I_D = I_{DSS} (1 - V_{GS}/V_P)^2$$



# Semiconductor Evolution for CATV

## Si vs. GaAs vs. GaN (on SiC substrate)

Property	Si	GaAs	SiC	GaN	Benefits
Energy Gap [eV]	1.11	1.43	3.2	3.4	High Voltage, Ruggedness
Charge Density ( $1 \times 10^{13}/\text{cm}^2$ )	0.3	0.3	0.4	1	High Current Density, Power Handling
Thermal Conductivity (W/cmK)	1.5	0.5	3.3	1.5	
Mobility ( $\text{cm}^2/\text{Vs}$ )	1300	6000	600	1500	High Frequency



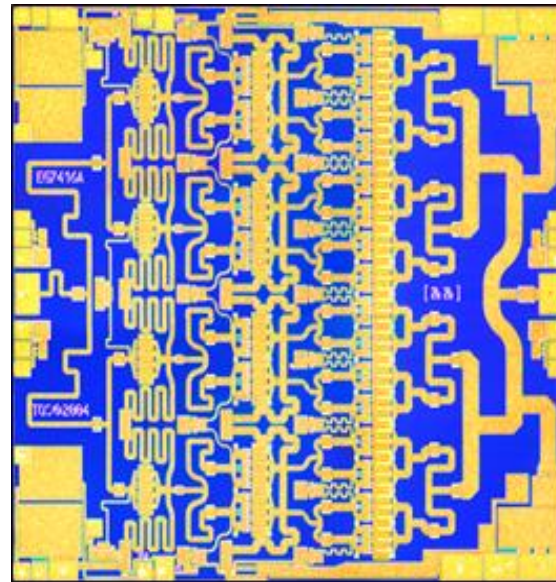
# Basics of GaN Devices

## Device Density & Thermal Benefits

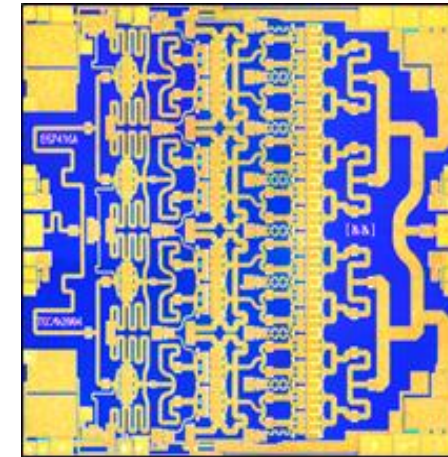
### SEMICONDUCTOR DEVICE DENSITY

GaN 10W/mm,  
Si-LDMOS 1.4W/mm,  
GaAs 1W/mm

- **Benefits of higher power density**
  - **Smaller geometry for given power level**
    - Lower device capacitances: higher bandwidths
    - Lower combining losses: higher gain & efficiency



GaAs (10x GaN)



Si-LDMOS (7.1x GaN)



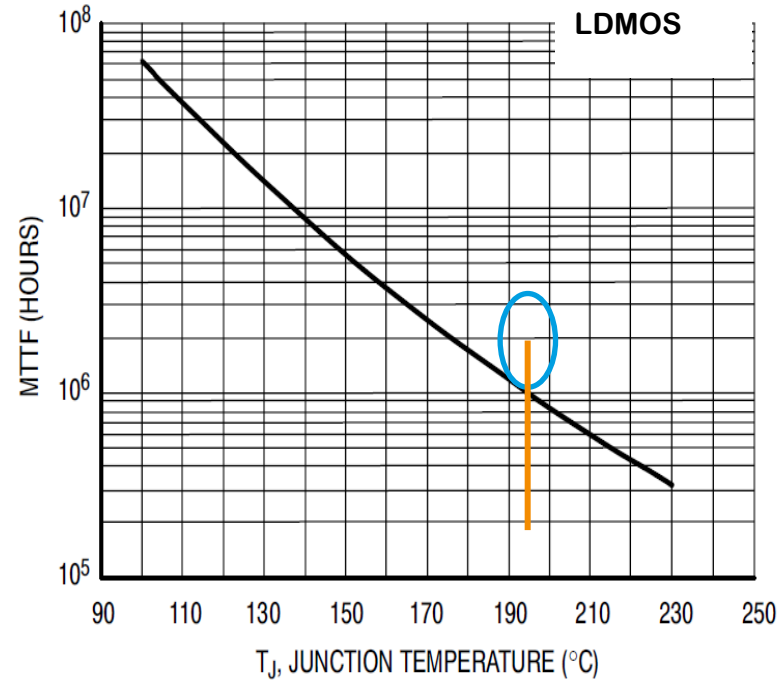
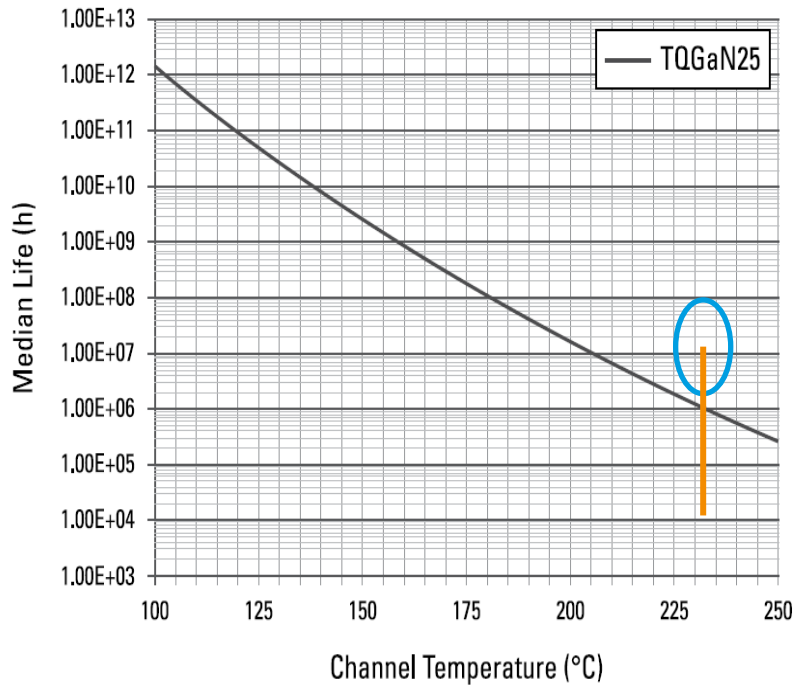
GaN



# Basics of GaN Devices

## Performance & Thermal Benefits

GaN on SiC devices offer higher power density and can operate at higher channel temperature and still offer  $1 \times 10^6$  MTTF reliability



Can dissipate more power without raising device temperature

Thermal Conductivity Comparison

GaAs ~ 0.52W/cm -°C

Si ~1.45W/cm -°C

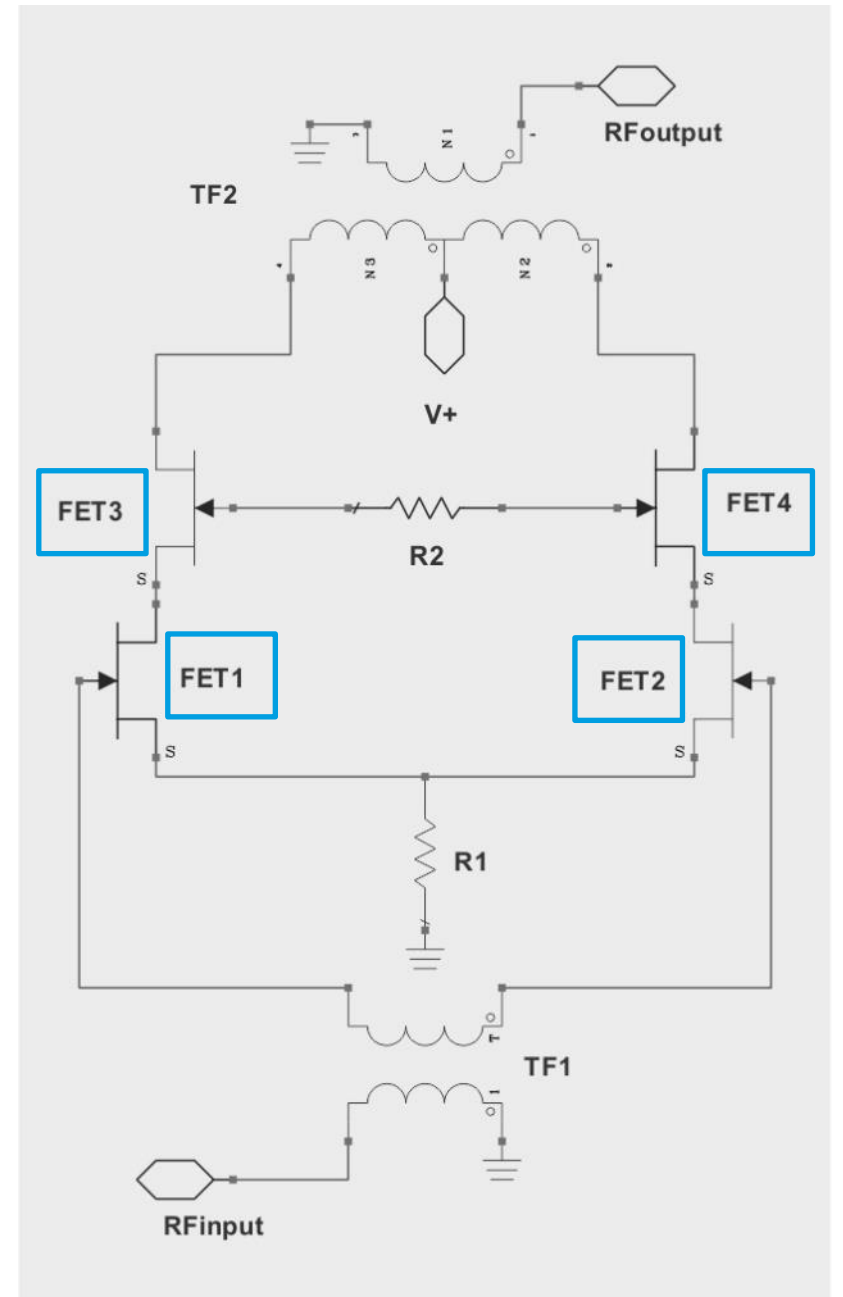
GaN - SiC ~ 3.30W/cm -°C



# Semiconductor Evolution for CATV

GaAs-based Gain Block

FET1 to FET4 = GaAs







# Semiconductor Evolution for CATV

## GaN enables CATV customers to:

- Increase the linear output power
  - Keep existing amplifier spacing, thereby minimizing upgrade cost
  - Enable Fiber Deep solutions
- Capable of reducing current by 20%, saving overall power
- Provide High Reliability
- Improved ruggedness compared to GaAs
- Offer mature designs: >20MU CATV GaN Die to date
- Amplifier Design for frequencies > 1.8GHz



# LINEARITY CHARACTERIZATION AND TEST DEVELOPMENT



# Distortion Parameters

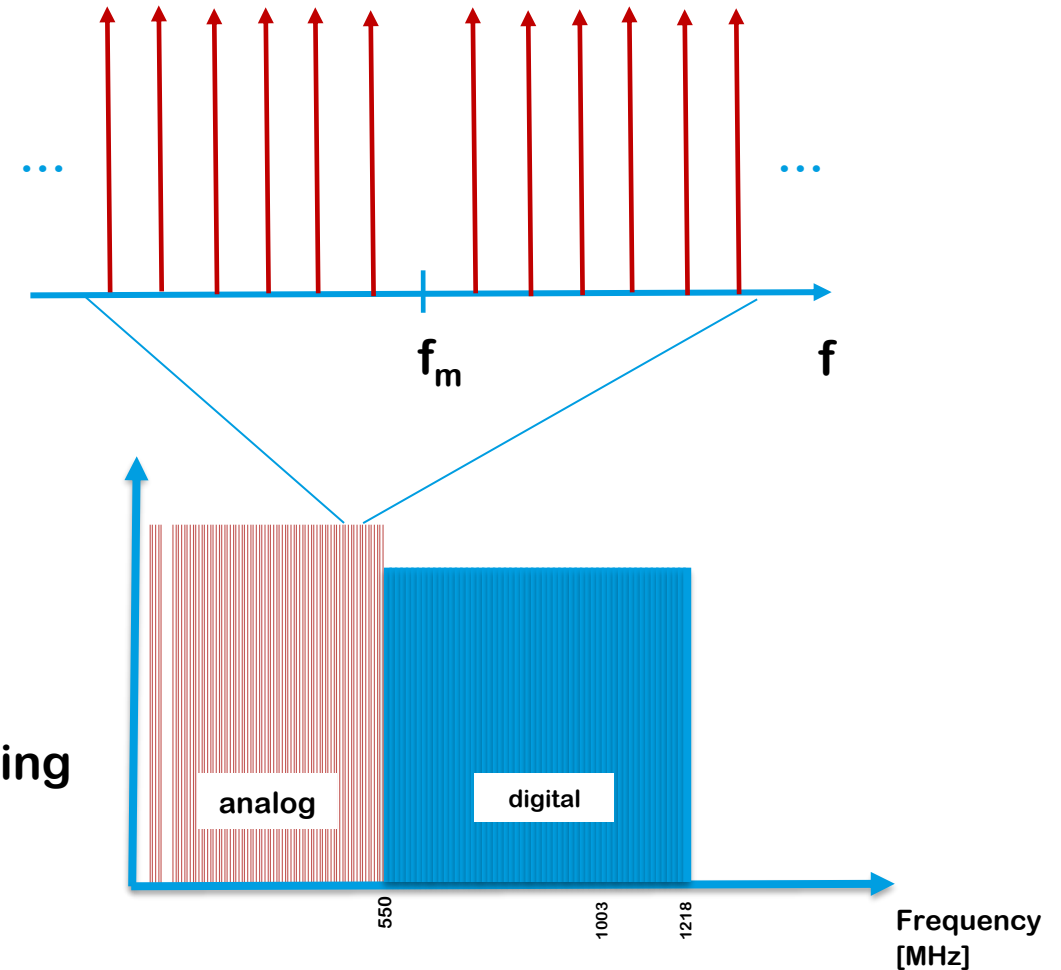
## Analog Band

CTB (Composite Triple Beat)

CSO (Composite Second Order)

XMod (Cross Modulation)

CCN (Carrier to Composite Noise)



# Distortion Parameters

## Digital Band

CCN (Carrier to Composite Noise)

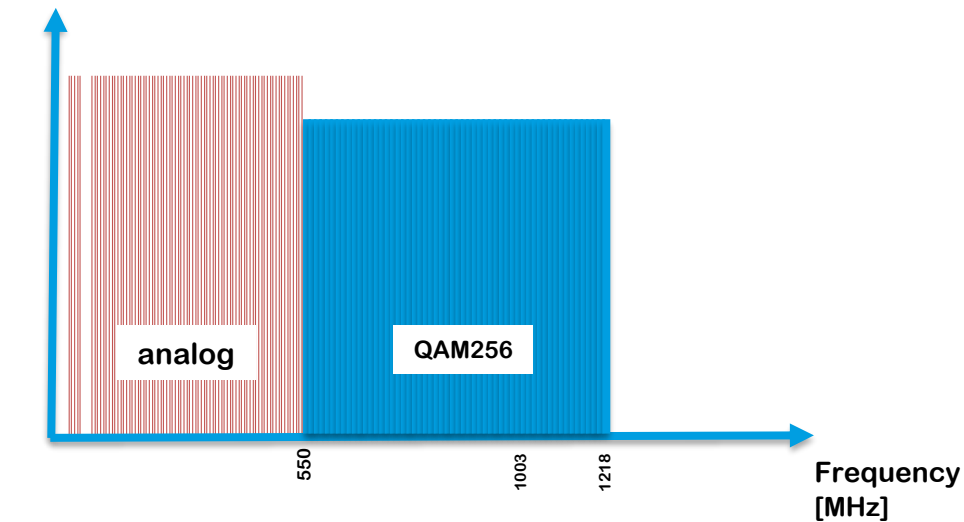
MER (Modulation Error Ratio):

$$\text{MER (dB)} = 10 \log_{10}(\frac{P_{\text{signal}}}{P_{\text{error}}})$$

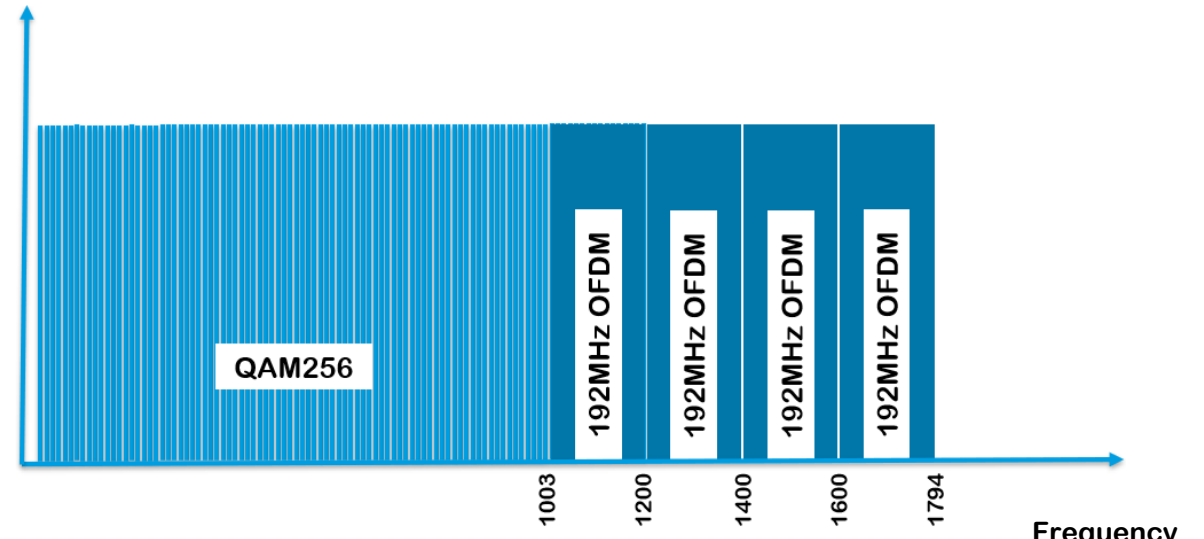
BER (Bit Error Ratio)

BER = Number of errors / total number of bits sent

### Channel Loading Examples for Digital Loading



Mixed Channel Loading (analog plus digital)

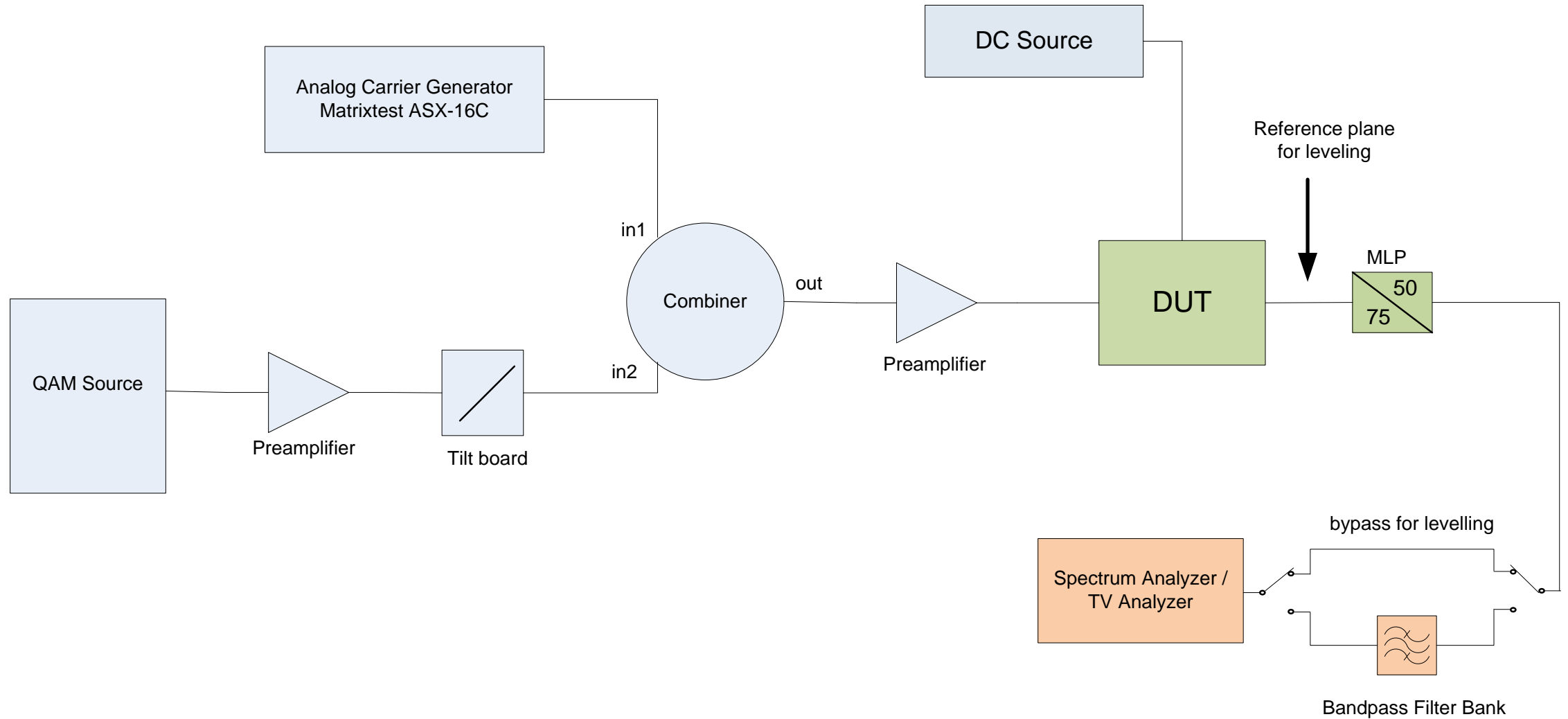


Pure Digital Loading (SC QAM and OFDM channels)



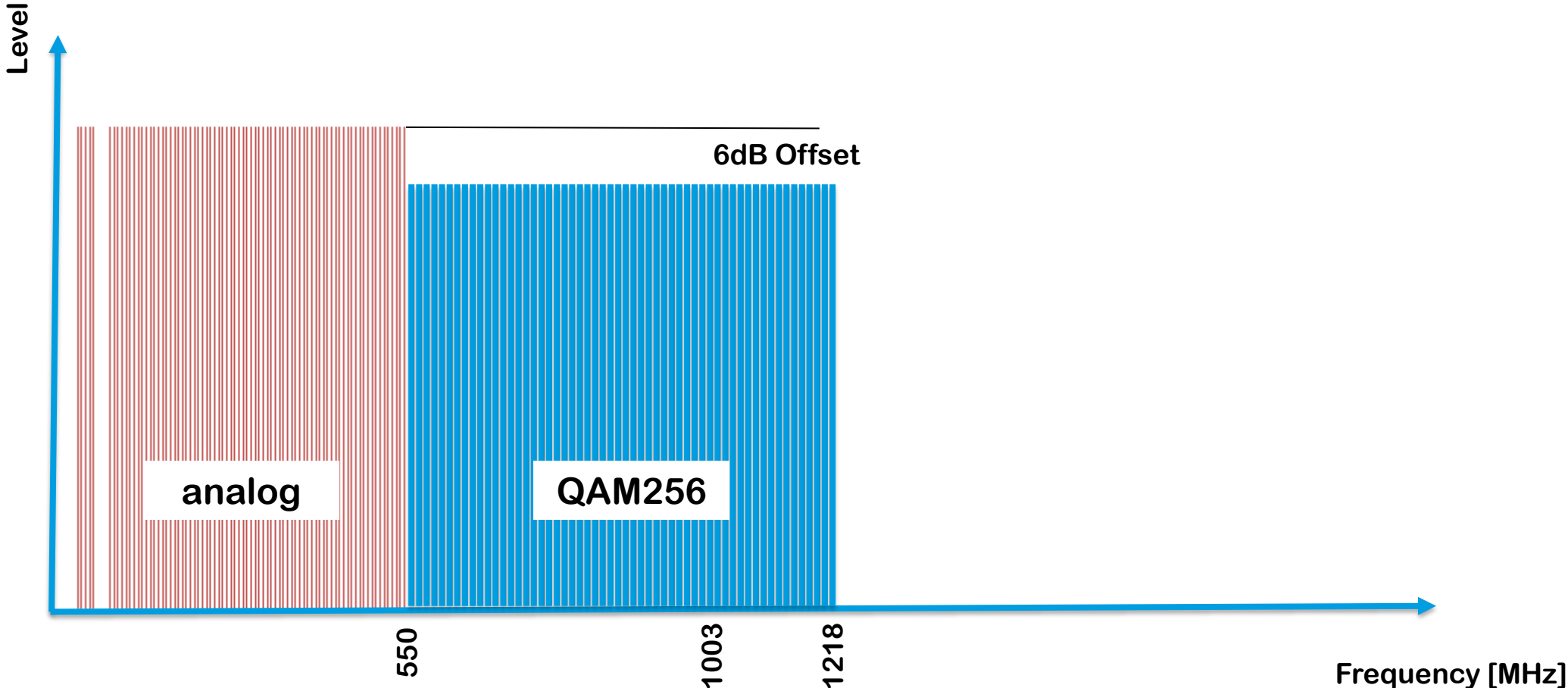
# DOCSIS 3.1 / 4.0 Testing

## Simplified Block Diagram



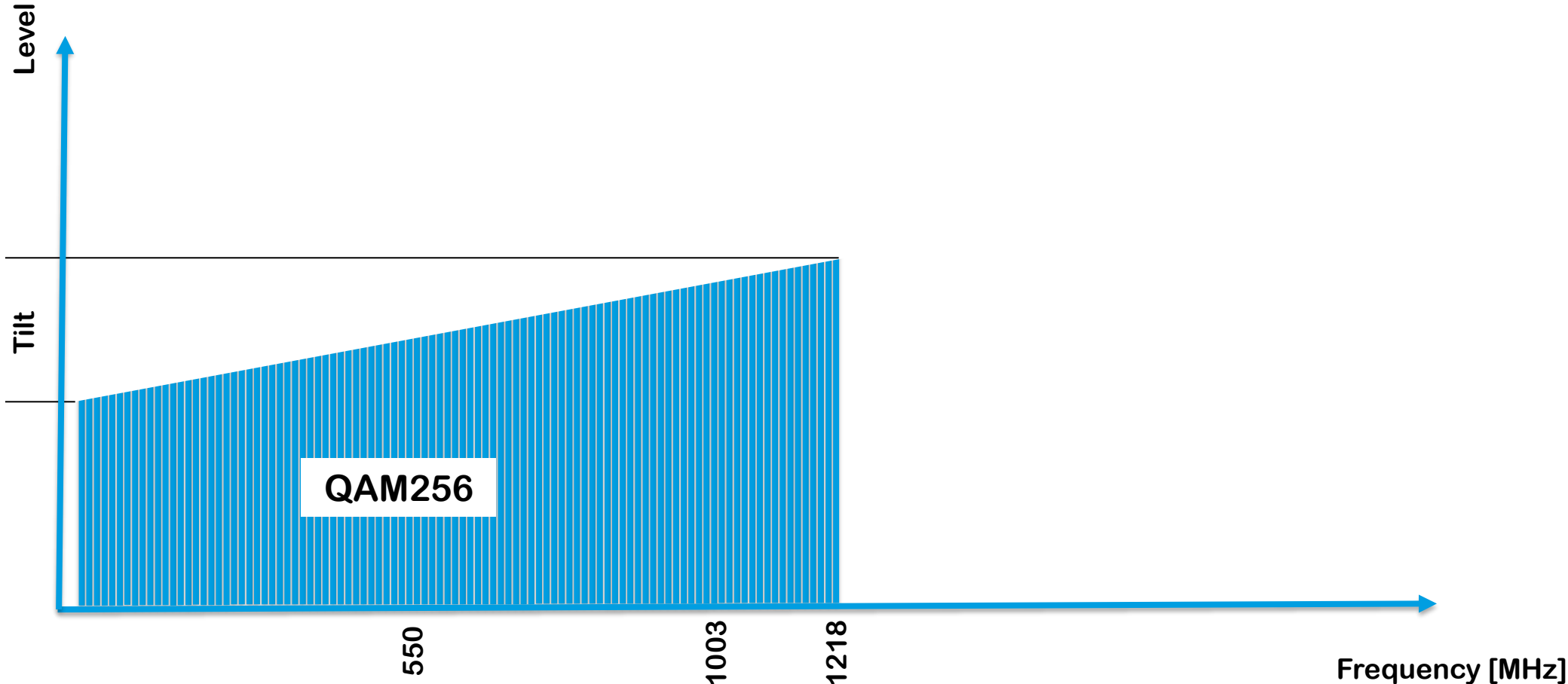
# Distortion Test Evolution

Loadings: Mixed Channel Loading (analog plus digital)



# Distortion Test Evolution

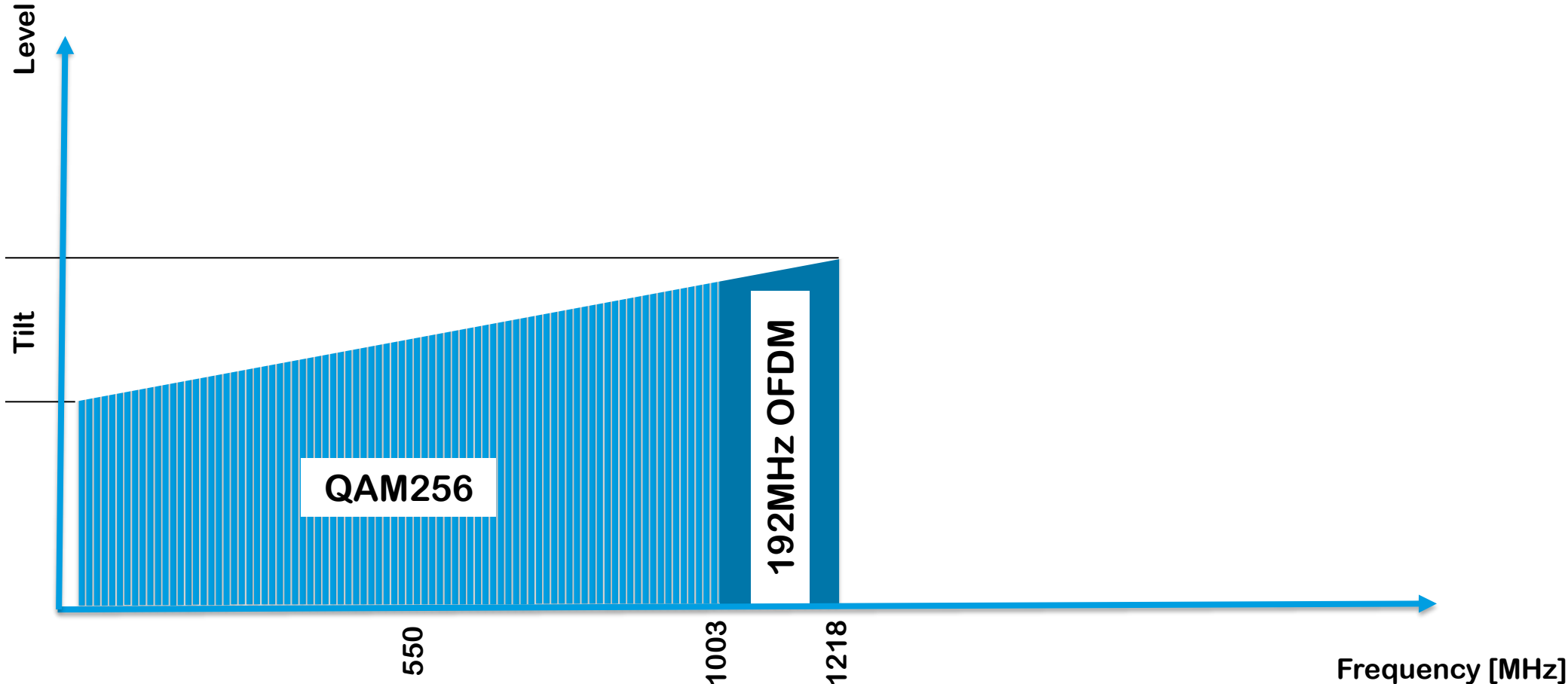
## Pure Digital Loadings





# Distortion Test Evolution

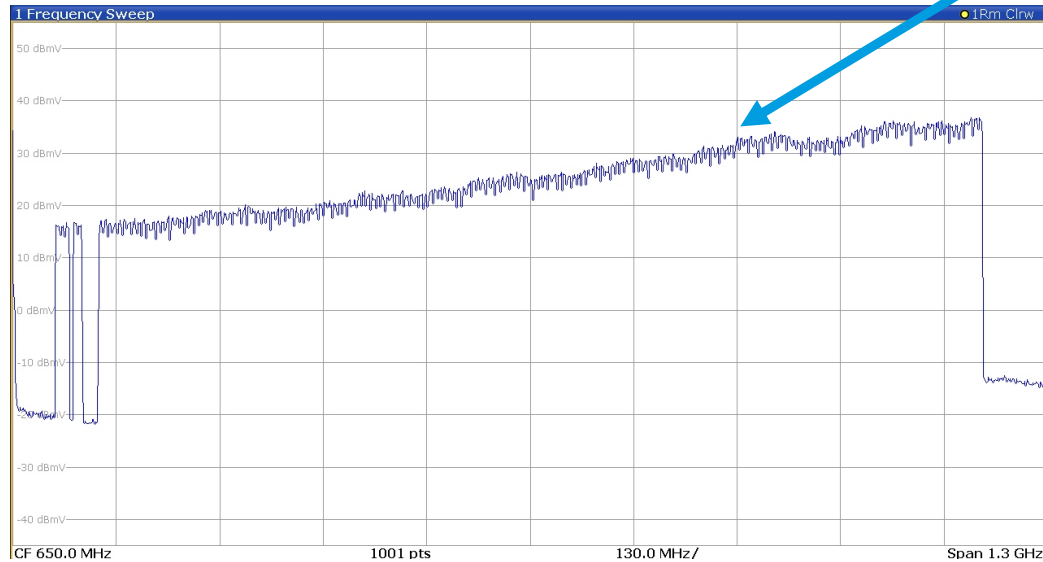
## DOCSIS 3.1 loading example



# DOCSIS Testing

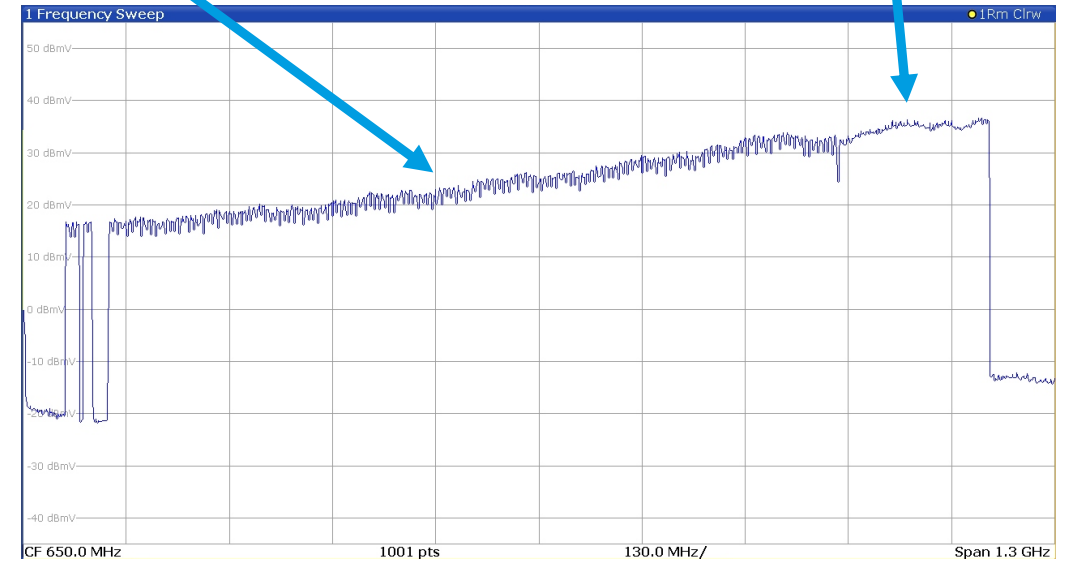
## QAM vs. QAM/OFDM Loading

QAM 256 channels



190 channels 256 QAM (ITU-T/J.83 Annex B)  
22dB tilt

192MHz OFDM channel

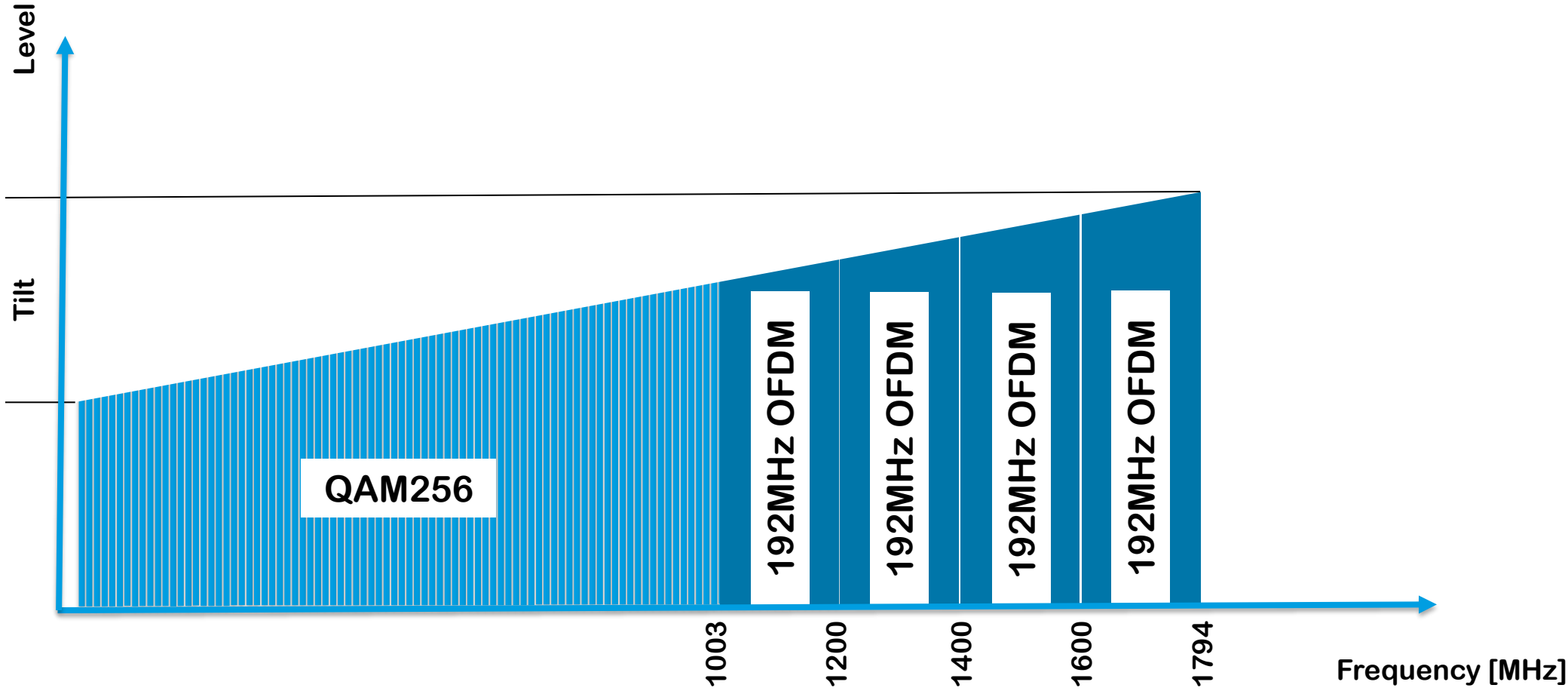


1 OFDM channel (192MHz) @1122MHz, QAM256 sub carriers  
+ 158 channels 256 QAM (ITU-T/J.83 Annex B)  
22dB tilt



# Distortion Test Evolution

DOCSIS 4.0 loading example



# HIGH VOLUME PRODUCTION ASSEMBLY AND TEST



# High Volume Production Assembly

Automation is key for multi million pcs./year production



- State of the art solder and epoxy connections to support a proper thermal design
- Automated assembly to ensure a reliable and reproducible performance
- Automated laser-trim and tune for as little as possible part to part variation



# High Volume Production Testing

## Full specification compliant testing

- 100% small signal and distortion test required
- Multi carrier (composite) distortion test
- Analog channel loading
  - → Mixed channel loading: analog plus digital channels
  - → Pure digital loading
    - → DOCSIS 3.1 → DOCSIS 4.0



[Watch video to learn more](#)







Thank You



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